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1. **Influence of axial chromatic aberration in projection printing**
Jain, P.K.; Neureuther, A.R.; Oldham, W.G.;
Electron Devices, IEEE Transactions on
Volume 28, Issue 11, Nov 1981 Page(s):1410 - 1416
IEEE JNL
2. **A Coaxial Interconnection System for High Speed Digital Processors**
Swengel, R., Sr.; Lemke, T.; Villiard, F.;
Parts, Hybrids, and Packaging, IEEE Transactions on
Volume 10, Issue 3, Sep 1974 Page(s):181 - 187
IEEE JNL
3. **New drive system and packaging method for magnetic bubble memory**
Hirota, K.; Akiba, Y.; Kawamoto, K.; Futami, T.;
Magnetics, IEEE Transactions on
Volume 21, Issue 5, Sep 1985 Page(s):1687 - 1690
IEEE JNL
4. **Differential board/backplane optical interconnects for high-speed digital systems. II. Simulation results**
Olsen, C.M.; Li, C.-S.;
Lightwave Technology, Journal of
Volume 11, Issue 7, July 1993 Page(s):1250 - 1262
IEEE JNL
5. **Adaptive threshold modulation for error diffusion halftoning**
Damera-Venkata, N.; Evans, B.L.;
Image Processing, IEEE Transactions on
Volume 10, Issue 1, Jan. 2001 Page(s):104 - 116
IEEE JNL
6. **Quantifying SMT decoupling capacitor placement in dc power-bus design for multilayer PCBs**
Jun Fan; Drewniak, J.L.; Knighten, J.L.; Smith, N.W.; Orlandi, A.; Van Doren, T.P.; Hubing, T.H.; DuBroff, R.E.;
Electromagnetic Compatibility, IEEE Transactions on
Volume 43, Issue 4, Nov. 2001 Page(s):588 - 599
IEEE JNL
7. **Memory efficient error diffusion**
Ti-chiun Chang; Allebach, J.P.;
Image Processing, IEEE Transactions on
Volume 12, Issue 11, Nov. 2003 Page(s):1352 - 1366
IEEE JNL
8. **Flip chip ball grid array component testing under board flexure**
Hsieh, G.; Mcallister, A.;
Electronic Components and Technology, 2005. ECTC '05. Proceedings
31 May-3 June 2005 Page(s):937 - 944 Vol. 1
IEEE CNF

9. **The metallic nickel inserted p/sup +/p/sup +/ Si substrate used for RF crosstalk reduction in mixed signal IC**
Xi Zhang; Kyuchul Chong; Ya-Hong Xie; King-Ning Tu;
Advanced Packaging Materials: Processes, Properties and Interfaces, 2005. Proceedings. International Symposium on
16-18 March 2005 Page(s):187 - 192
IEEE CNF
10. **Design and fabrication of air/semiconductor Bragg gratings for short wavelength nitride-based lasers**
Marinelli, C.; Sargent, L.J.; Bordovsky, M.; Wonfor, A.; Rorison, J.M.; Penty, R.V.; White, I.H.; Heard, P.J.; Benyouc M.; Kuball, M.; Hasnain, G.; Schneider, R.P.;
Lasers and Electro-Optics, 2001. CLEO '01. Technical Digest. Summaries of papers presented at the Conference o
6-11 May 2001 Page(s):82
IEEE CNF
11. **Measurement by vector-network analyzer and simulation of crosstalk reduction on printed circuit boards w additional center traces**
Novak, I.; Eged, B.; Hatvani, L.;
Instrumentation and Measurement Technology Conference, 1993. IMTC/93. Conference Record., IEEE
18-20 May 1993 Page(s):269 - 274
IEEE CNF
12. **Application of screen printing processes for epitaxial silicon thin-film solar cells**
Bau, S.; Rentsch, J.; Huljic, D.M.; Reber, S.; Hurre, A.; Willeke, G.;
Photovoltaic Energy Conversion, 2003. Proceedings of 3rd World Conference on
Volume 2, 12-16 May 2003 Page(s):1356 - 1359 Vol.2
IEEE CNF
13. **The theory of a singularity-enhanced FDTD method for diagonal metal edges**
Foroughipour, S.M.; Esselle, K.P.;
Antennas and Propagation, IEEE Transactions on
Volume 51, Issue 2, Feb. 2003 Page(s):312 - 321
IEEE JNL
14. **FE-BI analysis of a leaky-wave antenna with resistive sheet termination**
Kempel, L.; Schneider, S.; Radcliffe, J.; Janning, D.; Thiele, G.;
Wireless Communications and Applied Computational Electromagnetics, 2005. IEEE/ACES International Conferenc
on
3-7 April 2005 Page(s):670 - 673
IEEE CNF
15. **Demonstration for rapid prototyping of micro-systems packaging by data-driven chip-first process using nano-particles metal colloids**
Sungchul Joo; Baldwin, D.F.;
Electronic Components and Technology, 2005. ECTC '05. Proceedings
31 May-3 June 2005 Page(s):1859 - 1863 Vol. 2
IEEE CNF
16. **Automatic antenna tuning for RF transmitter IC applying high Q antenna**
Zolomy, A.; Mernyei, F.; Erdelyi, J.; Pardoen, M.; Toth, G.;
Radio Frequency Integrated Circuits (RFIC) Symposium, 2004. Digest of Papers. 2004 IEEE
6-8 June 2004 Page(s):501 - 504
IEEE CNF
17. **500 W QCW red laser**
Geels, R.S.; Major, J.S.; Welch, D.F.;
Lasers and Electro-Optics Society Annual Meeting, 1995. 8th Annual Meeting Conference Proceedings, Volume 1., IEEE

Volume 2, 30-31 Oct. 1995 Page(s):151 - 152 vol.2

IEEE CNF

18. **Compression flow modeling of underfill encapsulants for low cost flip chip assembly**
Pascarella, N.W.; Baldwin, D.F.;
Electronic Components and Technology Conference, 1998. 48th IEEE
25-28 May 1998 Page(s):463 - 470
IEEE CNF
19. **PCB Rogowski coils benefit relay protection**
Kojovic, L.;
Computer Applications in Power, IEEE
Volume 15, Issue 3, July 2002 Page(s):50 - 53
IEEE JNL
20. **Low cost, high performance RF substrates**
Santhanam, N.;
Technologies for Wireless Applications, 1999. Digest. 1999 IEEE MTT-S Symposium on
21-24 Feb. 1999 Page(s):65 - 68
IEEE CNF
21. **Applications of stress derating and thermal analysis to improve the reliability of electronic modules**
Radu, M.;
Electronics Technology: Integrated Management of Electronic Materials Production, 2003. 26th International Spring
Seminar on
8-11 May 2003 Page(s):26 - 30
IEEE CNF
22. **Magnetic properties of iron-cobalt alloy particles for magnetic recording media**
Uehori, T.; Hosaka, A.; Tokuoka, Y.; Izumi, T.; Imaoka, Y.;
Magnetics, IEEE Transactions on
Volume 14, Issue 5, Sep 1978 Page(s):852 - 854
IEEE JNL
23. **Xed: a new tool for extracting hidden structures from electronic documents**
Hadjar, K.; Rigamonti, M.; Lalanne, D.; Ingold, R.;
Document Image Analysis for Libraries, 2004. Proceedings. First International Workshop on
2004 Page(s):212 - 224
IEEE CNF
24. **Miniaturized synthetic rectangular waveguide**
Hsien-Shun Wu; Tzuang, C.-K.C.;
Microwave Symposium Digest, 2003 IEEE MTT-S International
Volume 2, 8-13 June 2003 Page(s):1099 - 1102 vol.2
IEEE CNF
25. **Step-and-repeat projection printing for VLSI circuit fabrication**
Binder, H.; Lacombe, M.;
Electron Devices, IEEE Transactions on
Volume 26, Issue 4, Apr 1979 Page(s):698 - 704
IEEE JNL

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Key: IEEE JNL = IEEE Journal or Magazine, IEE JNL = IEE Journal or Magazine, IEEE CNF = IEEE Conference, II CNF = IEE Conference, IEEE STD = IEEE Standard

26. Adaptive threshold error diffusion technique for color inkjet printing

Byonghyo Shim; Wonyong Sung;
Image Processing, 1997. Proceedings., International Conference on
Volume 1, 26-29 Oct. 1997 Page(s):779 - 782 vol.1

IEEE CNF

27. PCB Rogowski coil designs and performances for novel protective relaying

Kojovic, L.A.;
Power Engineering Society General Meeting, 2003, IEEE
Volume 2, 13-17 July 2003 Page(s):

IEEE CNF

28. Capacitive leadframe testing

Turner, T.T.;
Test Conference, 1997. Proceedings., International
1-6 Nov. 1997 Page(s):124

IEEE CNF

29. Capacitive leadframe testing

Turner, T.T.;
Test Conference, 1996. Proceedings., International
20-25 Oct. 1996 Page(s):925

IEEE CNF

30. Capacitive leadframe testing

Turner, T.T.;
Test Conference, 1995. Proceedings., International
21-25 Oct. 1995 Page(s):928

IEEE CNF

31. Multichip modules vs. high-density printed wiring boards: a trade-off study

O'Brien, D.E.; Hahne, B.M.; Krusius, J.P.;
Electronic Components and Technology Conference, 1992. Proceedings., 42nd
18-20 May 1992 Page(s):31 - 35

IEEE CNF

32. An optimization technique to minimize crosstalk in multi-layered and multi-microstrip-line board of high-speed digital circuits

Lin Lu; Ungvichian, V.;
Electromagnetic Compatibility, 1996. Symposium Record. IEEE 1996 International Symposium on
19-23 Aug. 1996 Page(s):442 - 447

IEEE CNF

33. An efficient approach for via minimization in multi-layer VLSI/PCB routing

Jong-Sheng Cherng; Sao-Jie Chen; Chia-Chun Tsai;
Custom Integrated Circuits Conference, 1995., Proceedings of the IEEE 1995
1-4 May 1995 Page(s):473 - 476.

IEEE CNF

34. A reduction camera for exposure of microcircuitry onto wafers

Wilczynski, J.S.; Tibbetts, R.E.; Harper, J.S.; Santy, W.G.;
Electron Devices Meeting, 1967 International
Volume 13, 1967 Page(s):146 - 146

IEEE CNF

35. The relationship between Image fidelity and Image quality

Silverstein, D.A.; Farrell, J.E.;
Image Processing, 1996. Proceedings., International Conference on
Volume 1, 16-19 Sept. 1996 Page(s):881 - 884 vol.1

IEEE CNF

36. Self-detectable serial test vector for short circuit fault detection

Kyongho Han; Hyun-Do Nam;
Information, Communications and Signal Processing, 1997. ICICS., Proceedings of 1997 International Conference
9-12 Sept. 1997 Page(s):1253 - 1256 vol.2

IEEE CNF

37. Analysis of high-speed bus lines in printed circuit boards

Satoh, H.; Matsui, N.; Okada, K.;
Electronic Manufacturing Technology Symposium, 1989, Proceedings. Japan IEMT Symposium, Sixth IEEE/CHMT
International
26-28 April 1989 Page(s):294 - 297

IEEE CNF

38. Test concept and experimental validation of the use of built-in-test to simplify conducted susceptibility testing of advanced technology integrated circuits and printed circuit boards

Daher, J.K.; Santamaria, J.C.; Herkert, R.M.;
Electromagnetic Compatibility, 1990. Symposium Record. 1990 IEEE International Symposium on
21-23 Aug. 1990 Page(s):113 - 117

IEEE CNF

39. An autonomous digital neural network architecture for segmenting hand-printed characters into visually pleasing and low variability sub-classes

Nellis, J.; Stonham, T.J.;
Neural Networks, 1991., IJCNN-91-Seattle International Joint Conference on
Volume ii, 8-14 July 1991 Page(s):931 vol.2

IEEE CNF

40. Active board concurrent maintenance

Makow, S.;
Electronic Components and Technology Conference, 1993. Proceedings., 43rd
1-4 June 1993 Page(s):468 - 469

IEEE CNF

41. Trends in electronic packaging and assembly for portable consumer products

Beelen-Hendriks, C.; Verguld, M.;
Electronics Packaging Technology Conference, 2000. (EPTC 2000). Proceedings of 3rd
5-7 Dec 2000 Page(s):24 - 32

IEEE CNF

42. An impedance matrix transformation for planar circuit integral equation solvers

Cervelli, F.; Mongiardo, M.; Tarricone, L.;
Microwave Symposium Digest, 1998 IEEE MTT-S International
Volume 3, 7-12 June 1998 Page(s):1559 - 1562 vol.3

IEEE CNF

43. An algorithmic approach to the improvement of efficiency for surface mounting machines

Hong, J.-M.; Lee, S.-H.; Kim, D.-W.; Lee, B.-H.; Kim, J.-D.; Kim, J.-O.;
Robotics and Automation, 1995. Proceedings., 1995 IEEE International Conference on
Volume 1, 21-27 May 1995 Page(s):806 - 811 vol.1

IEEE CNF

44. PCS antenna design: the challenge of miniaturisation

Staub, O.; Zurcher, J.-F.; Skrivervik, A.K.; Mosig, J.R.;
Antennas and Propagation Society International Symposium, 1999. IEEE
Volume 1, 11-16 July 1999 Page(s):548 - 551 vol.1

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